



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



General Descriptions

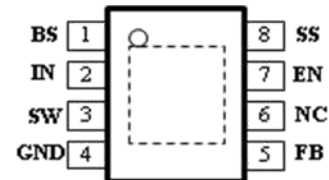
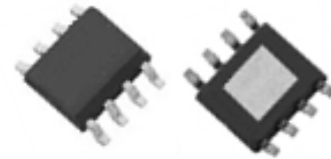
The NR120E series is buck regulator ICs integrates High-side power MOSFET. With the current mode control, ultra low ESR capacitors such as ceramic capacitors can be used. The ICs have protection functions such as Over-Current Protection (OCP), Under-Voltage Lockout (UVLO) and Thermal Shutdown (TSD). An adjustable Soft-Start by an external capacitor prevents the excessive inrush current at turn-on. The ICs integrate phase compensation circuit which reduces the number of external components and simplifies the design of customer application. The ON/OFF pin (EN Pin) turns the regulator on or off and helps to achieve low power consumption requirements. The NR120E series is available in an 8-pin SOIC package with an exposed thermal pad on the back side.

Features & Benefits

- Current mode PWM control
- Up to 94% efficiency
- Stable with low ESR ceramic output capacitors
- Built-in protection function
 - Over Current Protection (OCP)
 - Thermal Shutdown (TSD)
 - Under Voltage Lockout (UVLO)
- Built-in phase compensation
- Adjustable Soft-Start with an external capacitor
- Turn ON/OFF the regulator function

Package

- Exposed SOIC 8
- Thermally enhanced 8-Pin package



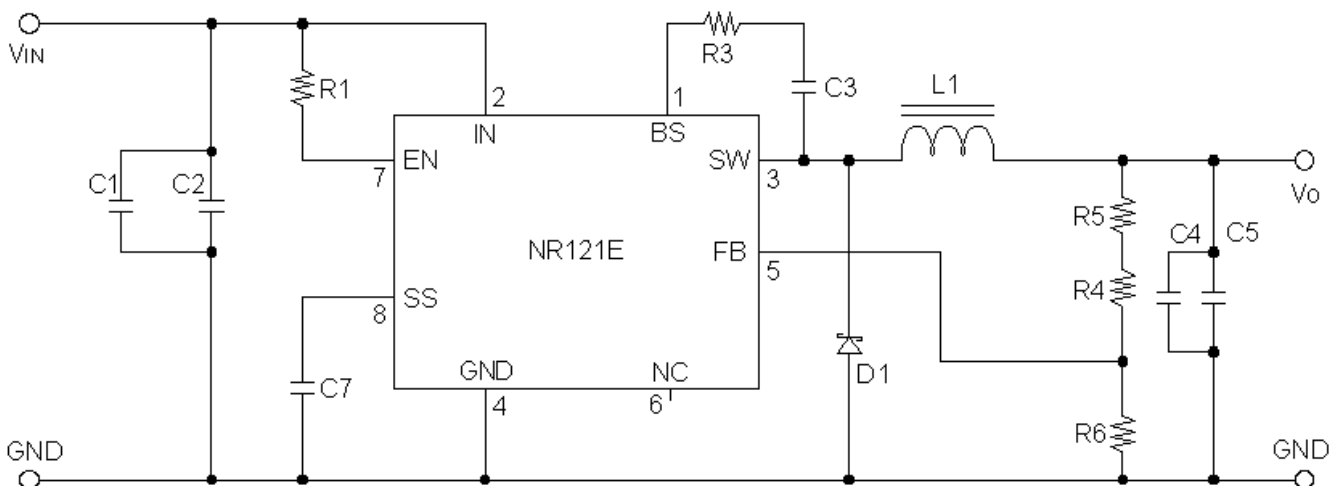
Electrical Characteristics

- 3A output current
- Operating input range $V_{IN} = 4.5V \sim 18V$
- Output adjustable $V_O = 0.8V \sim 14V$
- Fixed 350kHz frequency

Applications

- LCD TV / Blu-Ray / Set top box
- Green Electronic products
- Other power supply

Typical Application Circuit



C1, C2: 10 μ F / 25V
 C4, C5: 22 μ F / 16V
 C7: 0.1 μ F
 C3: 0.1 μ F

R1: 100k Ω
 R3: 22 Ω
 R4: 8.2 k Ω , R5: 4.3k Ω ($V_O=3.3V$)
 R6: 3.9k Ω

D1: SJPB-L4(Sanken)
 L1: 10 μ H

Series Lineup

Product No.	f_{sw}	V_{IN}	V_O	I_O
NR121E	350kHz	4.5V to 18V ⁽¹⁾	0.8V to 14V ⁽²⁾	3A

⁽¹⁾ The minimum input voltage shall be either of 4.5V or V_O+3V , whichever is higher.

⁽²⁾ The I/O condition limited by the Minimum on-time ($T_{ON(MIN)}$).

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Units	Conditions
DC input voltage	V_{IN}	20	V	
Power dissipation	P_D	1.76	W	Glass-epoxy board mounting in a 30×30mm. (copper area in a 25×25mm) Max $T_J = 150^\circ\text{C}$
Junction temperature	T_J	-40 to 150	$^\circ\text{C}$	
Storage temperature	T_S	-40 to 150	$^\circ\text{C}$	
Thermal resistance (junction- Pin No. 4)	θ_{JP}	26	$^\circ\text{C}/\text{W}$	
Thermal resistance (junction-ambient air)	θ_{JA}	71	$^\circ\text{C}/\text{W}$	Glass-epoxy board mounting in a 30×30mm. (copper area in a 25×25mm)

⁽³⁾ Limited by thermal shutdown.

⁽⁴⁾ The temperature detection of thermal shutdown is about 160°C

Recommended Operating Conditions

Parameter	Symbol	Ratings		Units	Conditions
		MIN	MAX		
DC input voltage	V_{IN}	V_O+3	18	V	
DC output current	I_O	0	3.0	A	
Output voltage	V_O	0.8	14	V	
Ambient operating temperature	T_{op}	-40	85	$^\circ\text{C}$	

⁽⁵⁾ The minimum value of input voltage is taken as the larger one of either 4.5V or $V_O + 3V$.

In the case of $V_{IN}=V_O+1 \sim V_O+3V$, it is set to $I_O = \text{Max. } 2A$

⁽⁶⁾ Recommended circuit refers to Typical Application Circuit.

⁽⁷⁾ To be used within the allowable package power dissipation characteristics

Electrical Characteristics

Ta = 25°C

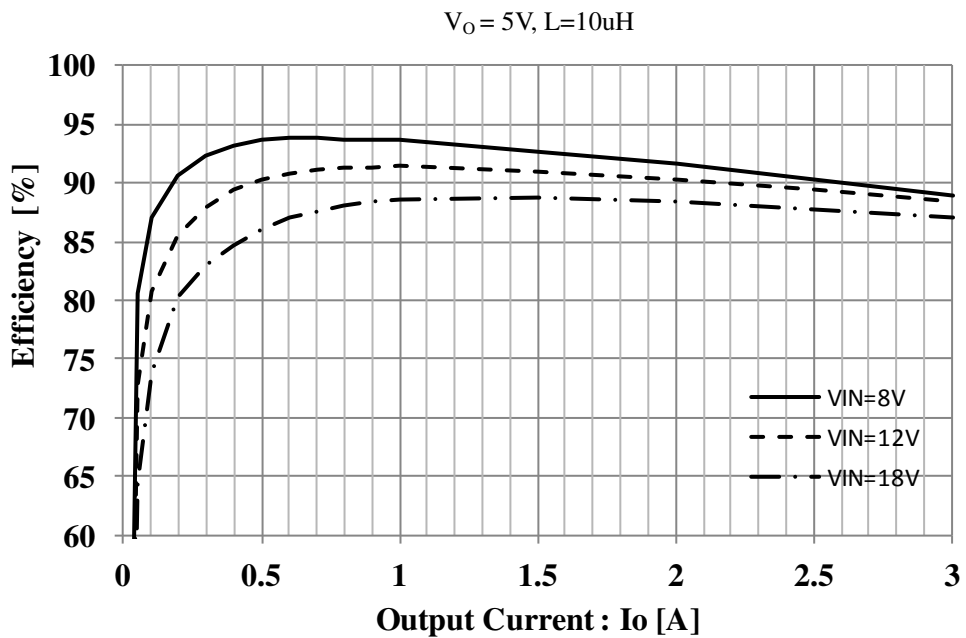
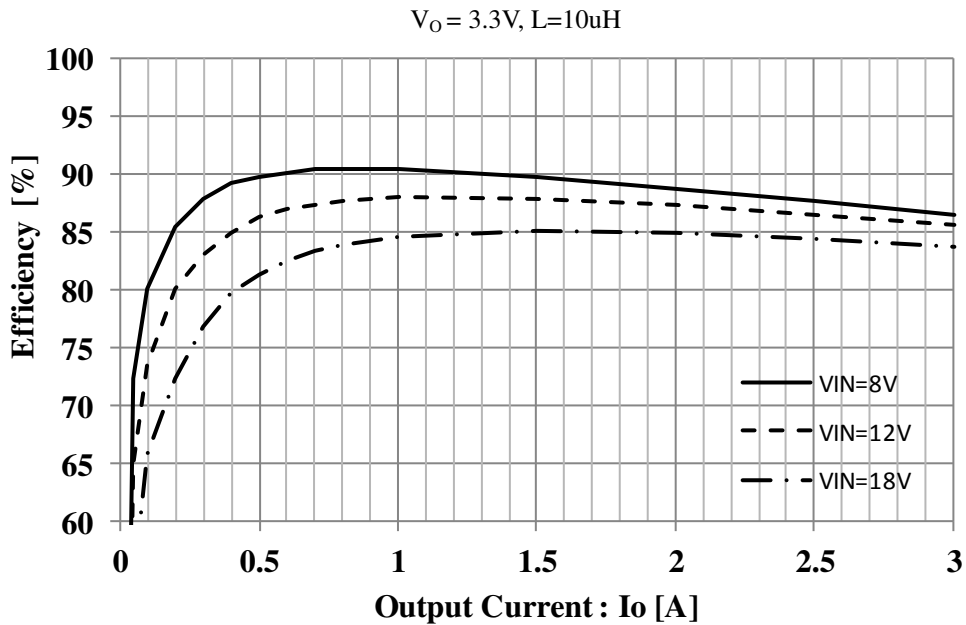
Parameter		Symbol	Ratings			Units	Test conditions
			MIN	TYP	MAX		
Reference voltage		V_{REF}	0.784	0.800	0.816	V	$V_{IN} = 12V, I_O = 1.0A$
Output voltage temperature coefficient		$\Delta V_{REF}/\Delta T$	—	± 0.05	—	mV/°C	$V_{IN} = 12V, I_O = 1.0A$ -40°C to +85°C
Switching frequency	NR121E	f_{SW}	280	350	420	kHz	$V_{IN} = 12V, V_O = 3.3V,$ $I_O = 1A$
Line regulation		⁽⁸⁾ V_{Line}	—	50	—	mV	$V_{IN} = 6.3V \sim 18V,$ $V_O = 3.3V, I_O = 1A$
Load regulation		⁽⁸⁾ V_{Load}	—	50	—	mV	$V_{IN} = 12V, V_O = 3.3V,$ $I_O = 0.1A \sim 3.0A$
Over current protection threshold		I_S	3.1	—	6.0	A	$V_{IN} = 12V, V_O = 3.3V$
Supply Current		I_{IN}	—	6	—	mA	$V_{IN} = 12V$ $V_{EN} = 10k\Omega$ pull up to V_{IN}
Shutdown Supply Current		$I_{IN(off)}$	0	—	10	μA	$V_{IN} = 12V, I_O = 0A,$ $V_{EN} = 0V$
SS Pin	Source current at low level voltage	$I_{EN/SS}$	6	10	14	μA	$V_{SS} = 0V, V_{IN} = 12V$
	High level voltage	V_{SSH}	—	3.0	—	V	$V_{IN} = 12V$
EN Pin	Sink current	I_{EN}	—	50	100	μA	$V_{EN} = 10V$
	Threshold voltage	$V_{C/EH}$	0.7	1.4	2.1	V	$V_{IN} = 12V$
Max on-duty		⁽⁸⁾ D_{MAX}	—	90	—	%	
Minimum on-time	NR121E	⁽⁸⁾ ⁽⁹⁾ $T_{ON(MIN)}$	—	150	—	nsec	
Thermal shutdown threshold temperature		⁽⁸⁾ TSD	151	165	—	°C	
Thermal shutdown restart hysteresis of temperature		⁽⁸⁾ TSD_hys	—	20	—	°C	

⁽⁸⁾ Guaranteed by design, not tested.⁽⁹⁾ The I/O characteristic are limited by the $T_{ON(MIN)}$.

Typical Performance Characteristics

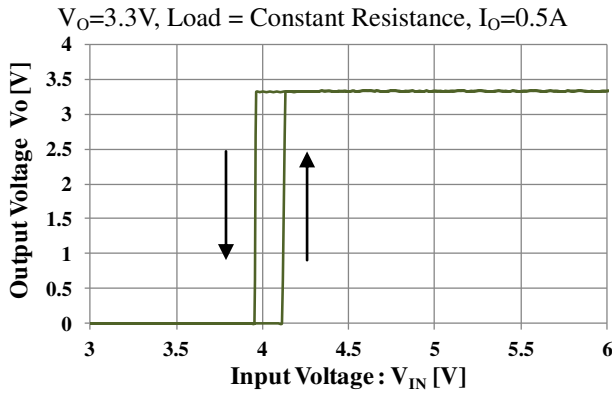
NR121E Typical Performance Characteristics

Efficiency

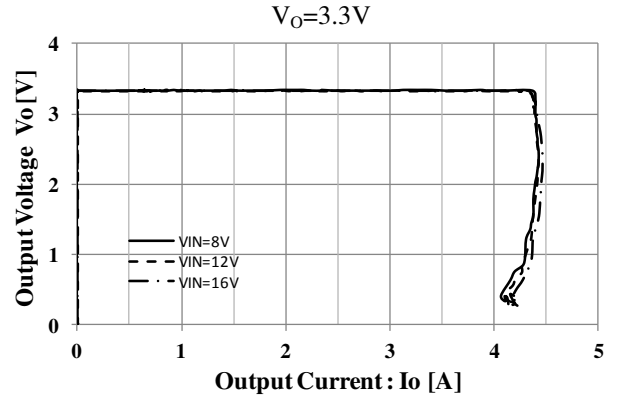


NR121E Typical Performance Characteristics

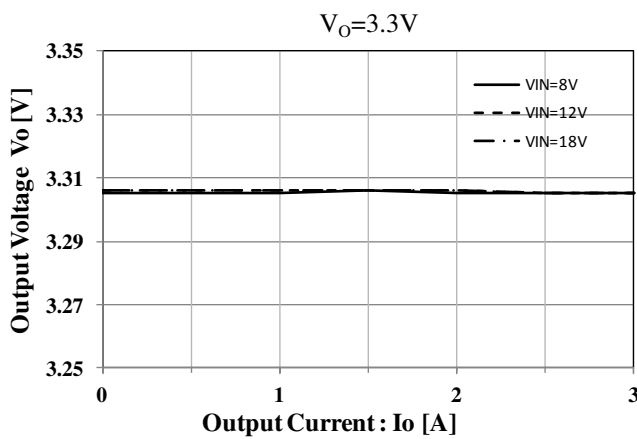
Output startup



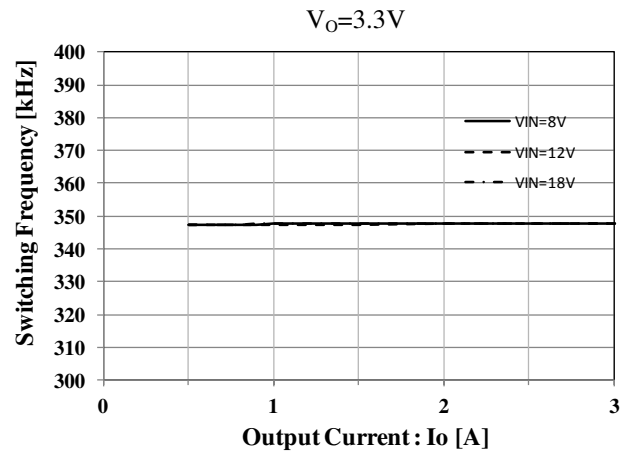
Over Current Protection



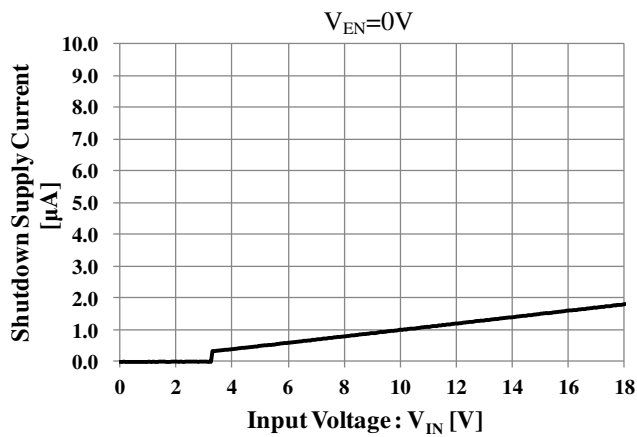
Load Regulation



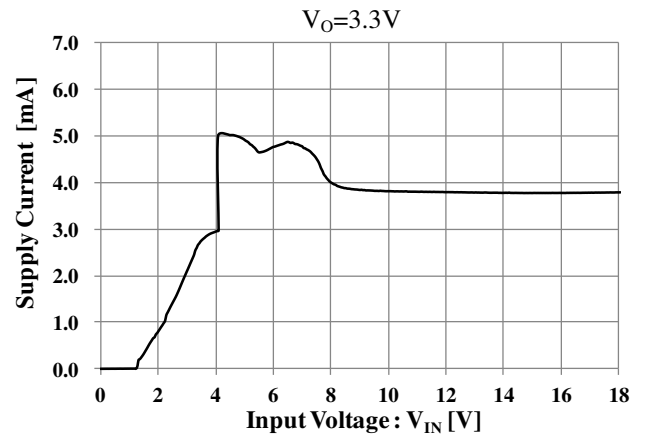
Switching Frequency



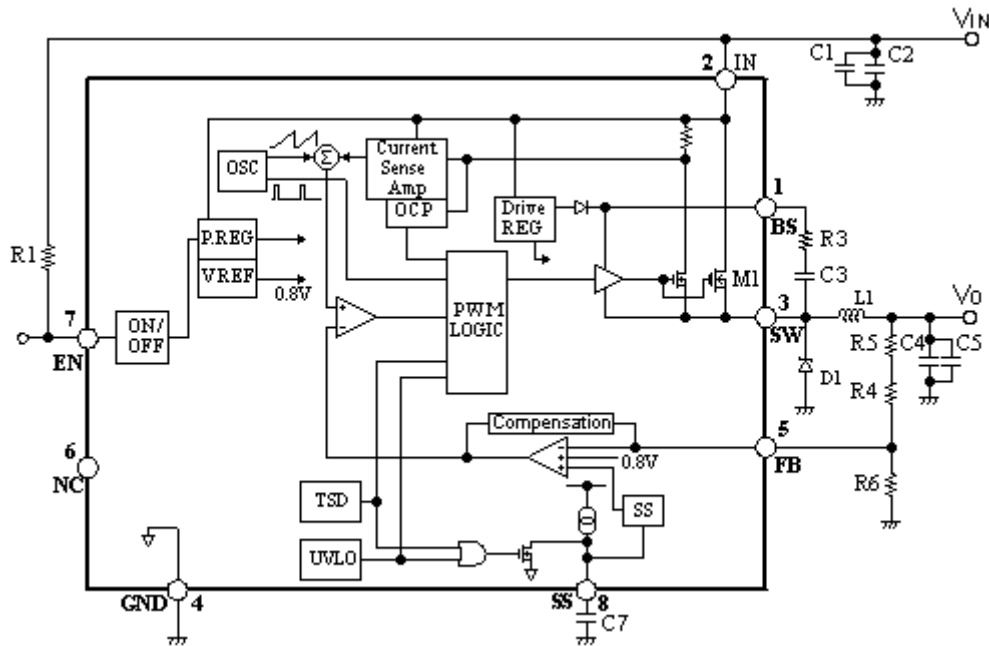
Shutdown Supply Current



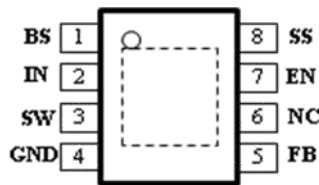
Supply Current



Functional Block Diagram



Pin Assignments & Functions



Pin Assignments

Pin Functions

Pin No.	Symbol	Description
1	BS	High-side Boost input. BS supplies the drive for High-side Nch-MOSFET switch. Connect a capacitor and a resistor between SW to BS.
2	IN	Power input. IN supplies the power to the IC.as well as the regulator switches
3	SW	Power switching output. SW supplies power to the output. Connect the LC filter from SW to the output. Note that a capacitor is required from SW to BS to supply the power the High-side switch
4	GND	Ground Connect the exposed pad to Pin No.4
5	FB	Feedback input Pin to compare Reference Voltage. The feedback threshold is 0.8V. To set the output voltage, FB Pin is required to connect between resistive voltage divider R4,R5 and R6.
6	NC	No Connection.
7	EN	Enable input. Drive EN Pin high to turn on the regulator, low to turn it off.
8	SS	Soft-Start control input. To set the soft-start period, connect to a capacitor between GND.

External Components Design Guide

(1) Diode D1

- The schottky-barrier diode must be used for D1. If other diodes like fast recovery diodes are used, IC may be damaged because of the reverse voltage applied by the recovery voltage or ON voltage.

(2) Choke coil L1

- If the winding resistance of the choke coil is too high, the efficiency may go down to the extent that it is out of the rating.
- As the start current of the over current protection is approximately 4A, attention must be paid to the heating of the choke coil by the magnetic saturation due to overload or short-circulated load.

(3) Capacitor C1(C2), C4(C5), C7

- As large ripple currents across C1 (C2) and C4 (C5), capacitors with high frequency and low impedance for SMPS must be used. Especially when the impedance of C4 (C5) is high, the switching waveform may not be normal at low temperature.
- C7 is a capacitor for soft start. A soft-start controls the over-shoot of the output voltage rising and rush current.

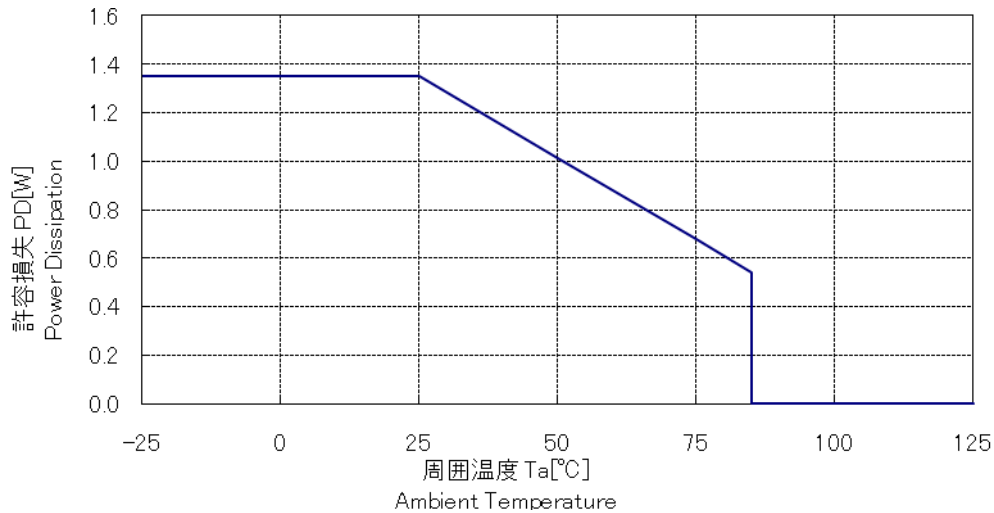
(4) Resistor R4, R5, R6

- R4, R5, R6 are resistor to the Output Voltage. I_{ADJ} is required to set to 0.2mA.
R4, R5, R6 are calculated by the equation (1).

$$R4 + R5 = \frac{(V_O - V_{FB})}{I_{ADJ}} = \frac{(V_O - 0.8)}{0.2 \times 10^{-3}} (\Omega), \quad R6 = \frac{V_{FB}}{I_{ADJ}} = \frac{0.8}{0.2 \times 10^{-3}} \approx 4.0k(\Omega) \quad \text{----- (1)}$$

In order to have optimum operating condition, each component must be connected with the minimum distance.

Allowable package power dissipation



NOTES

- 1) Glass-epoxy board mounting in a 30×30mm
- 2) copper area : 25×25mm
- 3) The power dissipation is calculated at the junction temperature 125 °C
- 4) Losses can be calculated by the following equation.
As the efficiency is subject to the input voltage and output current, it shall be obtained from the efficiency curve and substituted in percent
- 5) Thermal design for D1 shall be made separately.

$$P_D = V_O \cdot I_O \left(\frac{100}{\eta x} - 1 \right) - V_F \cdot I_O \left(1 - \frac{V_O}{V_{IN}} \right)$$

V_O : Output voltage

V_{IN} : Input voltage

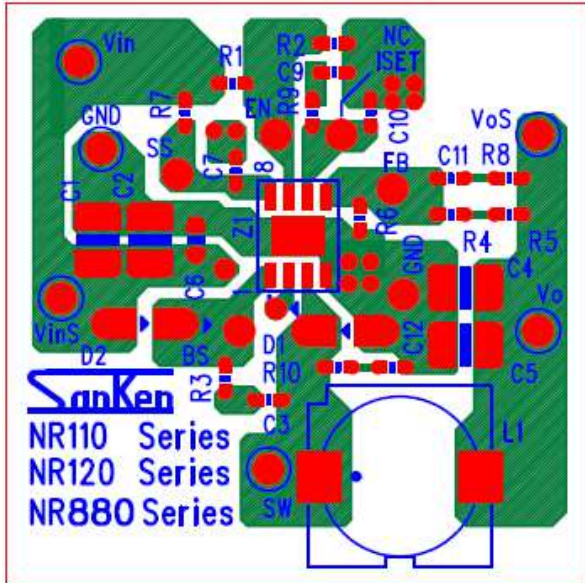
I_O : Output current

ηx : Efficiency(%)

V_F : Diode forward voltage
SJPB-L4...0.55V($I_O=3A$)

PCB Layout Example& Recommended Land Pattern

- (1) Each ground of all components is connected as close as possible to the Pin No.4 at one point.
- (2) To help heat dissipation, connect a large copper plane to exposed pad on the back side of the package.
The copper plane is required for GND

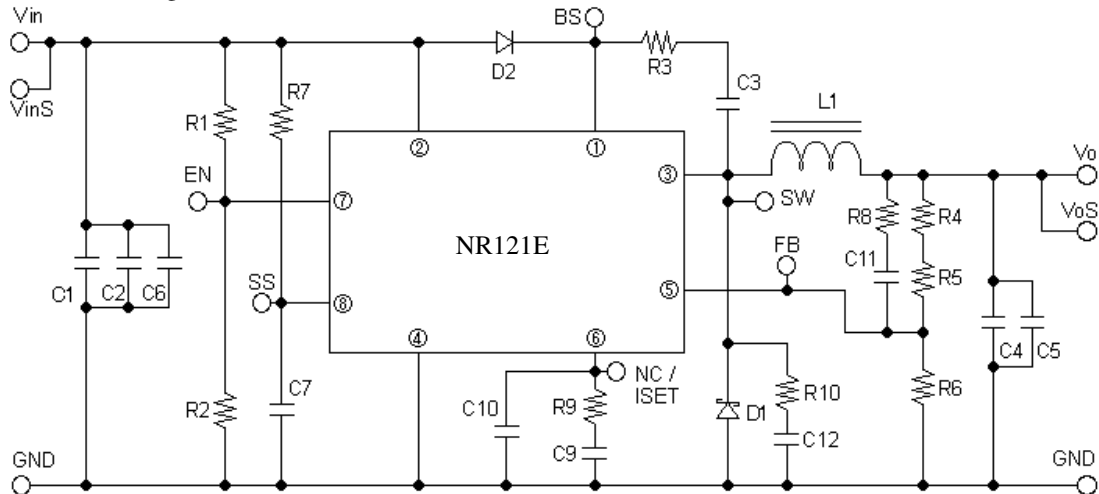


Front Side: Component Side (double sided board)



Back Side: GND Side (double sided board)

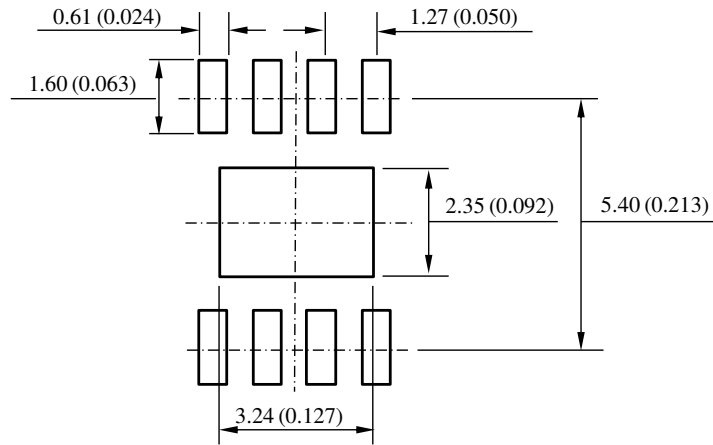
(Demo-board circuit-diagram)



As for the part number of the demonstration board "circuit-diagram", a circuit board concerned doesn't partly fit each other with the above application circuit example and so on for NR110, NR120 and the NR880 series common use. Approve it in advance. C9, R9 and C10 aren't used in the NR120 series. And, D2, R3, R8, R10, C11 and C12 are options.

NOTES:

Real size of the PCB is 60mm×60mm



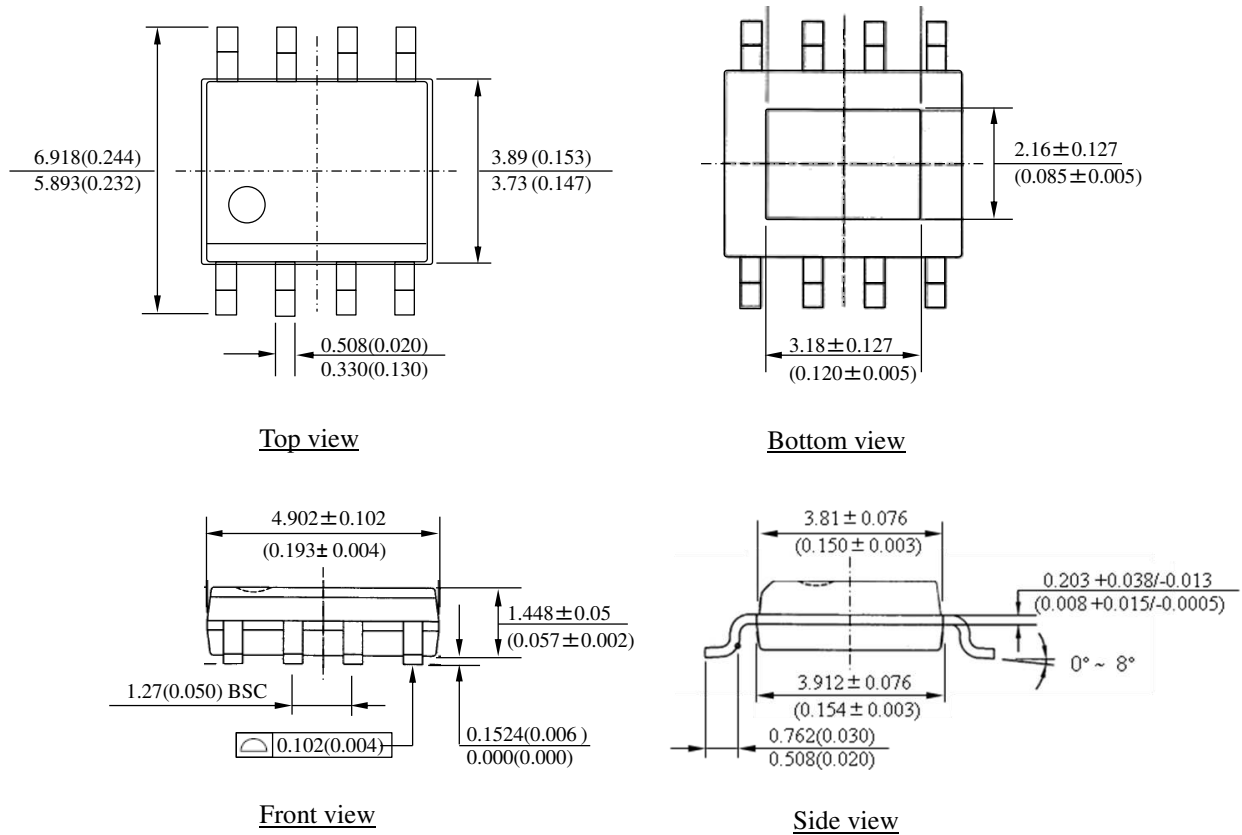
NOTES:

- 1) Dimension is in millimeters, dimension in bracket is in inches.
- 2) Drawing is not to scale.

Recommended land pattern

Package Outline

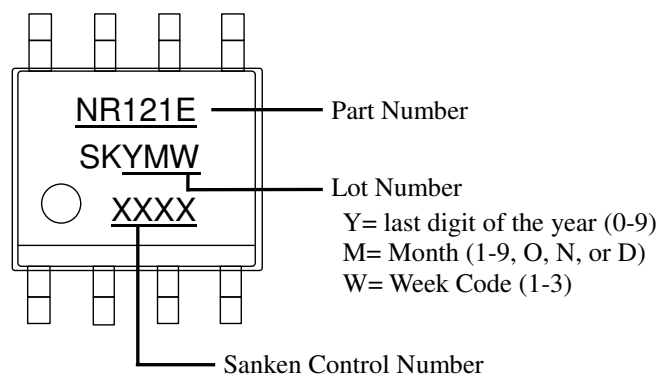
Exposed SOIC8 package



NOTES:

- 1) Dimension is in millimeters, dimension in bracket is in inches.
- 2) Drawing is not to scale.
- 3) Pb-free : Device composition comply with the RoHS directive.

Package Marking



OPERATING PRECAUTIONS

Reliability can be affected adversely by improper storage environments and handling methods. Please observe the following cautions.

Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5 to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of products that have been stored for a long time.

Cautions for Testing and Handling

- When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing products, shorts between the product pins, and wrong connections. In addition, avoid tests exceeded ratings

Soldering

When soldering the products, please be sure to minimize the working time, within the following limits.

- Reflow Preheat ; 180°C / 90±30s
Heat ; 250°C / 10±1s (260°C peak ,2times)
- Soldering iron ; 380±10°C / 3.5±0.5s (1time)

Electrostatic Discharge

- When handling the products, the operator must be grounded. Grounded wrist straps worn should have at least 1MΩ of resistance from the operator to ground to prevent shock hazard, and it should be placed near the operator.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of a soldering irons or the solder bath must be grounded in order to prevent leak voltages generated by them from being applied to the products.
- The products should always be stored and transported in Sanken shipping containers or conductive containers, or be wrapped in aluminum foil.

IMPORTANT NOTES

- The contents in this document are subject to changes, for improvement and other purposes, without notice. Make sure that this is the latest revision of the document before use.
- Application and operation examples described in this document are quoted for the sole purpose of reference for the use of the products herein and Sanken can assume no responsibility for any infringement of industrial property rights, intellectual property rights or any other rights of Sanken or any third party which may result from its use.
- Although Sanken undertakes to enhance the quality and reliability of its products, the occurrence of failure and defect of semiconductor products at a certain rate is inevitable. Users of Sanken products are requested to take, at their own risk, preventative measures including safety design of the equipment or systems against any possible injury, death, fires or damages to the society due to device failure or malfunction.
- Sanken products listed in this document are designed and intended for the use as components in general purpose electronic equipment or apparatus (home appliances, office equipment, telecommunication equipment, measuring equipment, etc.).
When considering the use of Sanken products in the applications where higher reliability is required (transportation equipment and its control systems, traffic signal control systems or equipment, fire/crime alarm systems, various safety devices, etc.), please contact your nearest Sanken sales representative to discuss, prior to the use of the products herein.
The use of Sanken products without the written consent of Sanken in the applications where extremely high reliability is required (aerospace equipment, nuclear power control systems, life support systems, etc.) is strictly prohibited.
- In the case that you use Sanken semiconductor products or design your products by using Sanken semiconductor products, the reliability largely depends on the degree of derating to be made to the rated values. Derating may be interpreted as a case that an operation range is set by derating the load from each rated value or surge voltage or noise is considered for derating in order to assure or improve the reliability. In general, derating factors include electric stresses such as electric voltage, electric current, electric power etc., environmental stresses such as ambient temperature, humidity etc. and thermal stress caused due to self-heating of semiconductor products. For these stresses, instantaneous values, maximum values and minimum values must be taken into consideration.
In addition, it should be noted that since power devices or IC's including power devices have large self-heating value, the degree of derating of junction temperature affects the reliability significantly.
- When using the products specified herein by either (i) combining other products or materials therewith or (ii) physically, chemically or otherwise processing or treating the products, please duly consider all possible risks that may result from all such uses in advance and proceed therewith at your own responsibility.
- Anti radioactive ray design is not considered for the products listed herein.
- Sanken assumes no responsibility for any troubles, such as dropping products caused during transportation out of Sanken's distribution network.
- The contents in this document must not be transcribed or copied without Sanken's written consent.